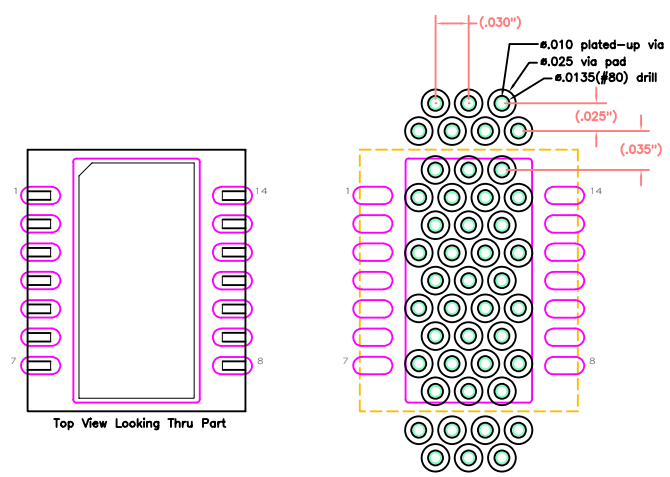
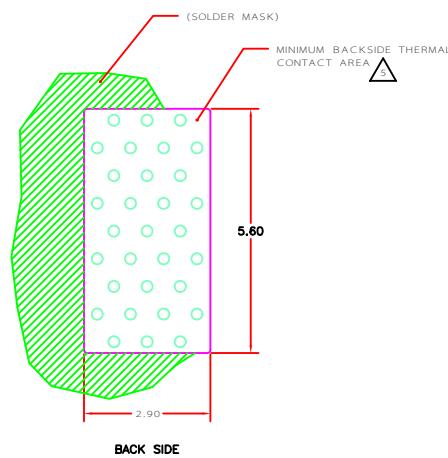
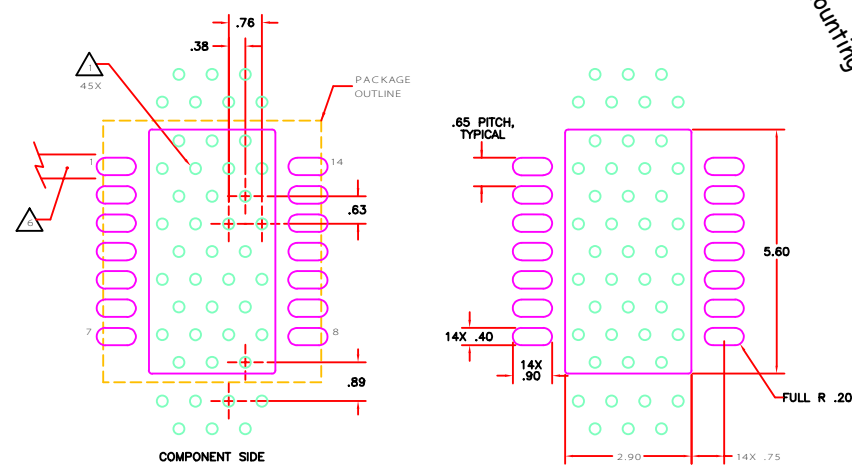
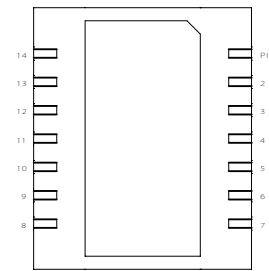
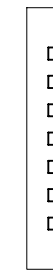


WJ Engineering Reference Info Only



Inches



Mounting Configuration / Land Pattern

- NOTES:
- △ GROUND/THERMAL VIAS ARE CRITICAL FOR THE PROPER PERFORMANCE OF THIS DEVICE. VIAS SHOULD USE A .35mm (#80/.0135") DIAMETER DRILL AND HAVE A FINAL, PLATED THRU DIAMETER OF .25mm (.010").
 - 2. ADD AS MUCH COPPER AS POSSIBLE TO INNER AND OUTER LAYERS NEAR THE PART TO ENSURE OPTIMAL THERMAL PERFORMANCE.
 - 3. TO ENSURE RELIABLE OPERATION, DEVICE GROUND PADDLE -TO- GROUND PAD SOLDER JOINT IS CRITICAL.
 - 4. ADD MOUNTING SCREWS NEAR THE PART TO FASTEN THE BOARD TO A HEATSINK. ENSURE THAT THE GROUND/THERMAL VIA REGION CONTACTS THE HEATSINK.
 - △ DO NOT PUT SOLDER MASK ON THE BACK SIDE OF THE PC BOARD IN THE REGION WHERE THE BOARD CONTACTS THE HEATSINK.
 - △ RF TRACE WIDTH DEPENDS UPON THE PC BOARD MATERIAL AND CONSTRUCTION.
 - 7. USE 1 OZ. COPPER MINIMUM.
 - 8. ALL DIMENSIONS ARE IN MILLIMETERS. ANGLES ARE IN DEGREES.

- NOTES:
- 1. EXCEPT WHERE NOTED, THIS PART OUTLINE CONFORMS TO JEDEC STANDARD MO-229, ISSUE C (VARIATION VJGC) FOR THERMALLY ENHANCED PLASTIC VERY THIN FINE PITCH QUAD FLAT NO LEAD PACKAGE (QFN).
 - 2. DIMENSIONING & TOLERANCING CONFORM TO ASME Y14.4M-1994.
 - 3. ALL DIMENSIONS ARE IN MILLIMETERS. ANGLES ARE IN DEGREES.
 - △ THE TERMINAL #1 IDENTIFIER AND TERMINAL NUMBERING CONVENTION CONFORM TO JESD 95-1 SPP-012.
 - △ COPLANARITY APPLIES TO THE EXPOSED GROUND/THERMAL PAD AS WELL AS THE TERMINALS.
 - △ PART NUMBER
 - △ ALPHA-NUMERIC LOT CODE.

Outline Drawing

